

DOUBLE-SIDED MULTI-CHIP CIRCUIT COMPONENT

Abstract

A multi-chip circuit component comprising first and second substrate members, each of which are formed of an electrically-nonconductive material. Each substrate member has oppositely-disposed first and second surfaces, with an outer layer of thermally-conductive material on the first surface thereof and electrically-conductive areas on the second surface thereof. At least two circuit devices are present between the first and second substrate members, with each circuit device having a first surface electrically contacting at least one of the electrically-conductive areas of the first substrate member, and each circuit device having a second surface electrically contacting a corresponding one of the electrically-conductive areas of the second substrate member. First lead members are electrically coupled to the electrically-conductive areas of the first substrate member, and second lead members are electrically coupled to the electrically-conductive areas of the second substrate member.